

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Vassoudevane Lebonheur et al.

Title: MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND
PROCESS OF MAKING SAME

Docket No.: 884,862US1

Serial No.: 10/612,764

Filed: June 30, 2003

Due Date: June 13, 2006

Examiner: Victor A. Mandala

Group Art Unit: 2826

MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

X Amendment and Response Under 37 CFR 1.111 (16 pgs.).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

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(GENERAL)